WORKSHOP ON NUMERICAL MODELING OF PROCESSES AND DEVICES FOR INTEGRATED CIRCUITS

Santa Clara, California

Nov. 13-14, 1986

CALL FOR PAPERS

TECHNICAL PROGRAM COMMITTEE

Robert W. Dutton, Chairman Dimitri A. Antoniadis Steven E. Laux Jerry Mar Andrew R. Neureuther Mark R. Pinto Donald J. Rose Andrzej J. Strojwas Ping Yang

Under the joint sponsorship of the Circuits and Systems Society of the IEEE and in conjunction with ICCAD, a workshop on the numerical modeling of processes and devices for integrated circuits will be held in Santa Clara, CA on Thursday, Nov. 13, 1986 through Friday, Nov. 14, 1986.

The program will consist of 20-minute presentations selected from descriptive extended abstracts. Topics could include: process simulation; device modeling and simulation of complex structures; device modeling for circuit simulation; algorithms and software; integration of process, device and circuit simulation; simulation of detailed physical phenoména; comparison of simulation for different semiconductor technologies. A workshop environment will be encouraged, and papers should not duplicate ICCAD submissions.

THE DEADLINE FOR ABSTRACT SUBMISSION IS MAY 31, 1986. Abstracts should include a brief summary statement (50 words) and a more detailed description not to exceed 500 words or two pages including figures. Applicants will be notified of the committee's decision by August 15, 1986. Prospective speakers should send ten copies of their extended abstracts to:

> Robert W. Dutton AEL 204 Stanford University Stanford, CA 94305 (415) 497-4138

All speakers will have the opportunity to publish a written version of their presentation, subject to review, in a future issue of the IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems. Deadline for submission of manuscripts will be January 1, 1987. Manuscripts should be sent to Robert W. Dutton.

Final program and meeting details will be mailed in September, 1986.

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ELECTRON DEVICES

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IEEE ELECTRON DEVICE LETTERS is published monthly with the purpose of providing rapid publication of original and significant contributions relating to the theory, design, and performance of electron and ion devices, solid-state devices, integrated electronic devices, optoelectronic devices, and energy sources. Publication time will be two months from the end of the month in which it was received providing the author responds immediately to all communications. Galley proofs will be sent, but in the interest of fast publication, there may not be time to wait for their return. Errata will be published in the next issue if sent promptly. Lengths of the letters are expected to be no longer than two printed pages.

Manuscripts: An original and three copies of the manuscript must be submitted, each complete with all illustrations, to the editor (see inside front cover). The manuscript must include an abstract limited to about 100 words. The two printed page limit permits about 1800 words of text in addition to the title, abstract, and references. The amount of text will be reduced by allowance for equations, tables, and figures. An average one-column figure with its caption will displace about 220 words of text. In some cases, lengths of between two and two and one-half pages may be justified. A submission containing the equivalent of more than two and one-half pages will be returned for shortening immediately and not be given an official received date. The manuscript should be double spaced on only one side of each 22×28 cm sheet. Good office machine copies are acceptable. The style for references, abbreviations, etc., can be determined from previous issues of this journal or the IEEE TRANSACTIONS ON ELECTRON DEVICES. A pamphlet, "Information for IEEE Authors," is available on request from the IEEE Editorial Department, 345 East 47th St., New York, NY 10017. Prospective authors are urged to read this and follow its recommendation on the organization of their paper.

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References should be started on a separate sheet of paper, and must be double-spaced. Figure captions should be started on a separate sheet of paper, and must be double-spaced. Do not include captions on the illustrations themselves, since captions are set in type separately. Figure captions should be sufficiently clear so that the figures can be understood without detailed reference to the accompanying text. Axes of graphs should have self-explanatory labels, not just symbols (e.g., Electric Field rather than E.)

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